

**SUBJECT: ECW-U (B) Series, Film Chip Capacitor**

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**Date: Aug. 6, 2007 Page 1 of 1**

**Last Time Buy: January 1<sup>st</sup>, 2008**

**Last Time Ship: March 31<sup>st</sup>, 2008**

**RECOMMENDED REPLACEMENT:** ECH-U(X), ECW-U(X) or ECW-U(C)

**DETAILS:**

The “**B**” suffix was the original design for the SMT Film Chip. The termination was made by applying metallic spray on the surface of the cap. This left a flat surface with no rounding off on the edge of the termination. This may cause tomb stoning under certain soldering conditions, particularly with small case sizes, i.e.: < 1913, capacitors.

The “**X**” suffix termination however, is made by dipping the capacitor into a conductive resin. The conductive resin creates rounded contour around the edges of the cap. This design minimizes the potential of tomb stoning for the small size film capacitors.

The “**C**” suffix series has the original flat surface termination, since no tomb stoning occurs with larger case sizes than 1210. It uses a different stacking process to prevent peering of some surface layers.

Please refer to the chart below for our recommendations:

| Soldering Methods | Old                           | Recommended Series                         |   |
|-------------------|-------------------------------|--|---|
| Wave              | ECW-U( B )<br>16, 50, 100 Vdc | —  | —   |
| Reflow            |                               | ECW-U( C )<br>16, 50, 100,<br>250, 400 Vdc | ECW-U( X )<br>100 Vdc<br>ECH-U( X )<br>10, 16, 50 Vdc |